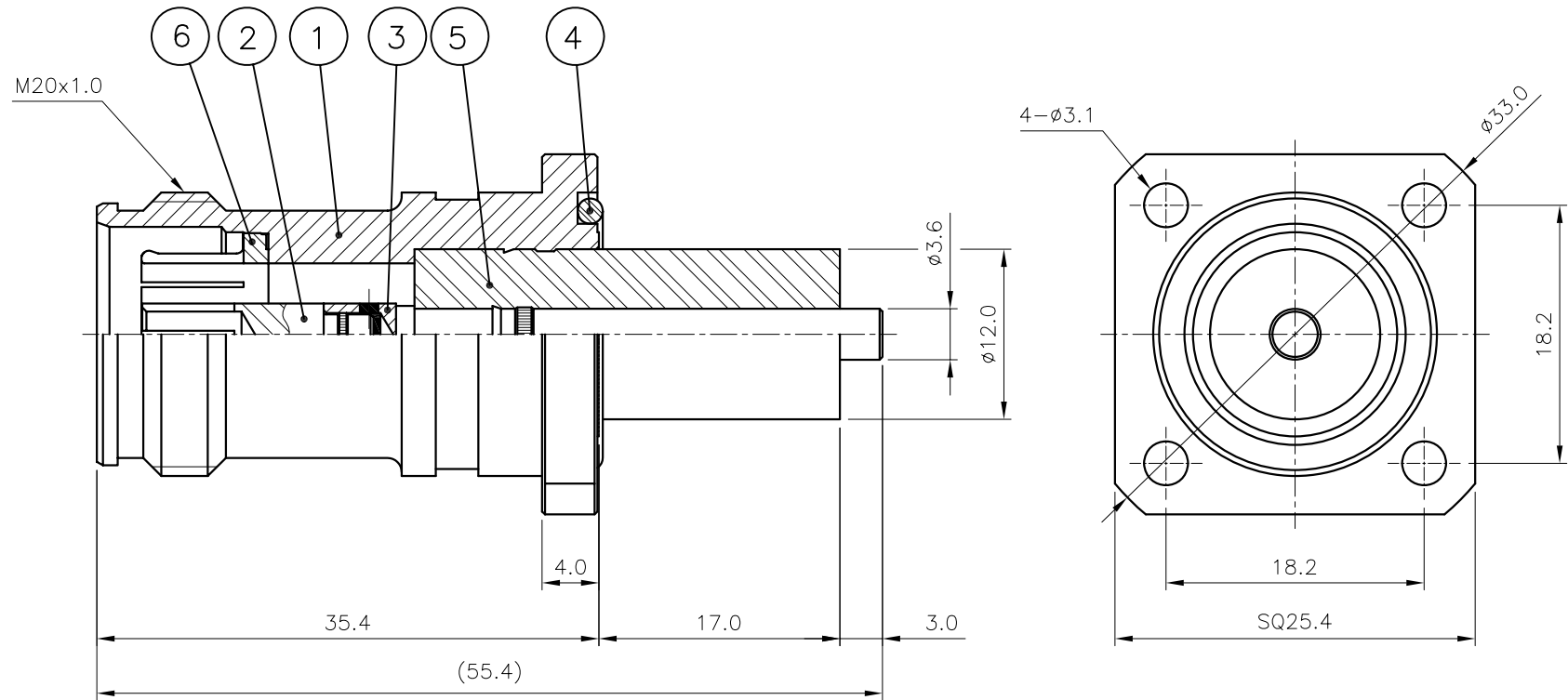


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2017. 12. 28.



6	JACK	1	MBsBD C3604BD-F	Silver Plate (3 μ m)	DJA00228-5/6
5	INSULATOR	1	TEFLON		DIN02966-N/1
4	GASKET	1	SILICONE RUB		DGK00045-N/1
3	CONTACT	1	MBsBD C3604BD-F	Silver Plate (3 μ m)	DCT03902-5/1
2	CONTACT	1	BeCu C17300	Silver Plate (3 μ m)	DCT03901-5/1
1	BODY	1	MBsBD C3604BD-F	SUCO Plate	DBD04369-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

* 조립방법 *

1. ①번 BODY와 ⑥번 JACK을 조립한다.
2. ②번 PIN과 ③번 PIN을 억지끼움 후 SOLDER한다.
3. BODY에 ⑤번 절연체를 조립 후 PIN을 조립한다.
4. ④번 GASKET 조립한다.

TOLERANCE	Decimal	DATE 2017. 12. 28.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE 4.3-10 DIN50 SOLDER END JS-4H
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	2/1	A4 DWG NO. CN03752-7/1 REVISION I R SHEET 1 of 1
		UNIT	mm	